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(54) Title: COMPOSITION FOR METAL ELECTROPLATING COMPRISING AN ADDITIVE FOR BOTTOM-UP FILLING OF THOUGH SILICON VIAS AND INTERCONNECT FEATURES

(57) Abstract: A composition comprising a source of metal ions and at least one polyaminoamide, said polyaminoamide comprising amide and amine functional groups in the polymeric backbone and aromatic moieties attached to or located within said polymeric backbone.

